

Title (en)

METHOD FOR MAKING AN INTEGRATED CIRCUIT CAPABLE OF BEING SURFACE-MOUNTED AND RESULTING CIRCUIT

Title (de)

HERSTELLUNGSVERFAHREN FÜR EINEN AUF EINER OBERFLÄCHE MONTIERBAREN INTEGRIERTEN SCHALTKREIS UND DADURCH HERGESTELLTER SCHALTKREIS

Title (fr)

PROCEDE DE FABRICATION DE CIRCUIT INTEGRE DE TYPE MONTABLE EN SURFACE ET CIRCUIT ISSU DU PROCEDE

Publication

**EP 1314196 A1 20030528 (FR)**

Application

**EP 00953253 A 20000718**

Priority

FR 0002063 W 20000718

Abstract (en)

[origin: WO0207208A1] The invention concerns a method for making an integrated circuit (40) capable of being surface-mounted which consists in first making a housing with a rear face and an array of connection pins extending underneath said rear surface perpendicular thereto, and then in forming at the end of each pin a ball (44) of alloy with low melting point enclosing said end and welded thereto. The invention also concerns an integrated circuit (40) capable of being surface-mounted, comprising a housing with a rear surface and an array of connection pins, with substantially constant cross-section along the pin, extending underneath said rear surface perpendicular thereto. A ball (44) of alloy with low melting point is welded to the end of each pin (42) enclosing said end. The invention is applicable to surface-mounted integrated circuits.

IPC 1-7

**H01L 21/48**; **H01L 23/498**

IPC 8 full level

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CPC (source: EP KR US)

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